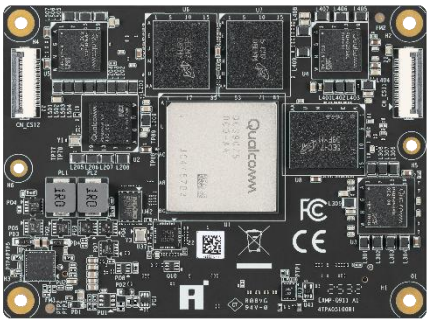
COMPUTING INTELLIGENCE

QUALCOMM IQ9 SERIES

innodisk



EXMP-Q911 Preliminary

HIGHLIGHT FEATURES

- Powered by Qualcomm Dragonwing IQ-9075
- Provides up to 100 TOPS of AI processing performance at low power with Hexagon NPU
- Accelerates AGV, AMR, and LLM applications at the edge with unparalleled performance
- 128GB UFS 3.1 storage, up to 36GB onboard memory
- Dual 2.5G Ethernet, dual 4-lane MIPI CSI-2
- COM-HPC Mini form factor
- Longevity: Chipset supported through 2038

SPECIFICATIONS

Model Name	EXMP-Q911
Module Form Factor	COM-HPC Mini
CPU	QCS9075 (Octa-core Kryo Gen 6 : 8x Kryo Gold Prime @2.36GHz)
Graphics	Adreno 663 GPU
Memory	36GB LPDDR5X
Storage	128GB UFS 3.1
AI Engine	100 TOPS (Dense) / 200 TOPS (Sparse) via 2 x Hexagon Tensor Processor
Expansion	1 x PCIe Gen 4 x4 1 x PCIe Gen 4 x2
MIPI	2 x 4-lane MIPI CSI-2 (22pin, P: 0.5, on module)
Ethernet	2 x 2.5 GbE LAN
Display	2 x DP1.2 1 x eDP
Audio	1 x I²S for Headphone / AMP
I/O Interfaces	2 x USB 3.2 Gen 2 x1 (10Gbps) 4 x USB 2.0 2 x UART (1 with CTS / RTS) 1 x COM (RS232 / 422 / 485, on module) 1 x SPI (General SPI) 1 x CAN FD 4 x I²C (1 x on module, 3.3V) 12 x GPIO
Power Requirement	8 ~ 20V DC Power Supply
Security	TPM 2.0
OS Support	Yocto Linux; Ubuntu
Other Features	• Fan Supply : PWM Speed Control for CPU Fan on Carrier Board • System Monitoring : CPU Temperature, CPU Fan
Temperature	Operating : -40°C ~ 85°C (Ta) Storage : -40°C ~ 95°C (Ta)
Humidity	Operating & Storage : 5% to 95%, Non-condensing
Vibration	3G, IEC 60068-2-64, Random Vibration, 5 ~ 500Hz, 1hr/axis
Shock	30G, IEC 60068-2-27, Half Sine, 11ms Duration
ESD	EN61000-4-2, Air-15kV, Contact-8kV

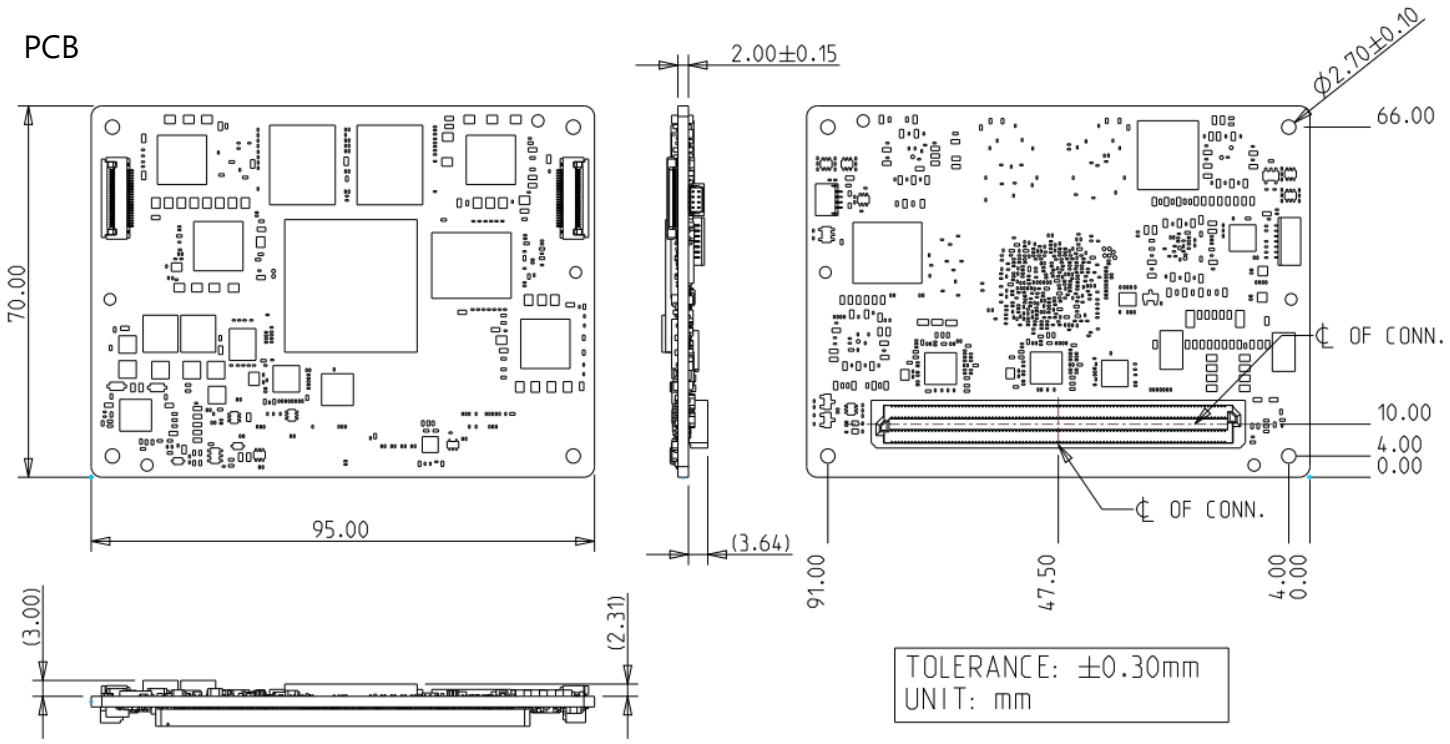
Certification	CE / FCC Class B
Warranty	2 Years
Weight(g)	53.3
Dimensions (W x L/mm)	95 x 70mm

ORDER INFO.

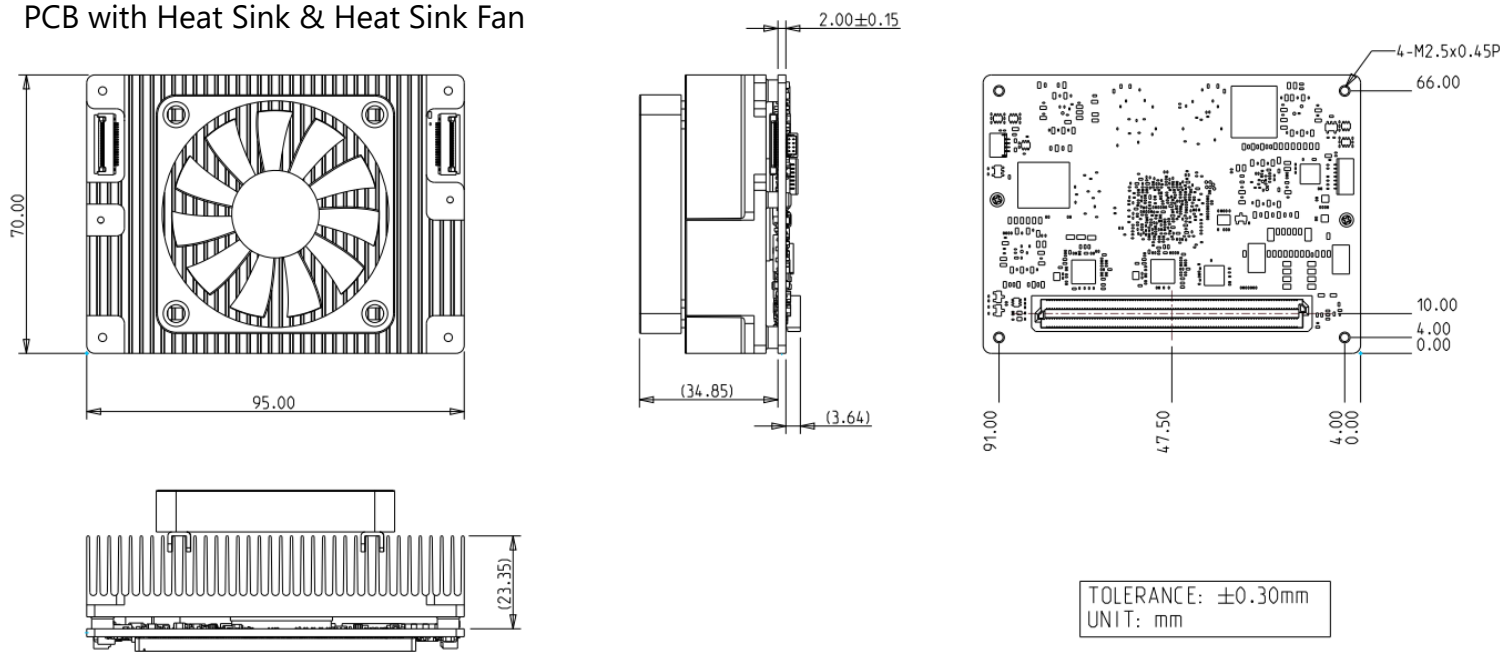
P/N	Description
EXMP-Q911-00A1-W1	COM-HPC Mini Module, Qualcomm IQ9075, 36GB RAM, 128GB UFS, 100 TOPS, 8 ~ 20V DC, -40°C ~ 85°C, 95 x 70mm
EXMP-Q911-00A1-W2	COM-HPC Mini Module, Qualcomm IQ9075, 36GB RAM, 128GB UFS, 100 TOPS, 8 ~ 20V DC, -40°C ~ 85°C, W/ Cooler, 95 x 70mm

MECHANICAL DRAWING

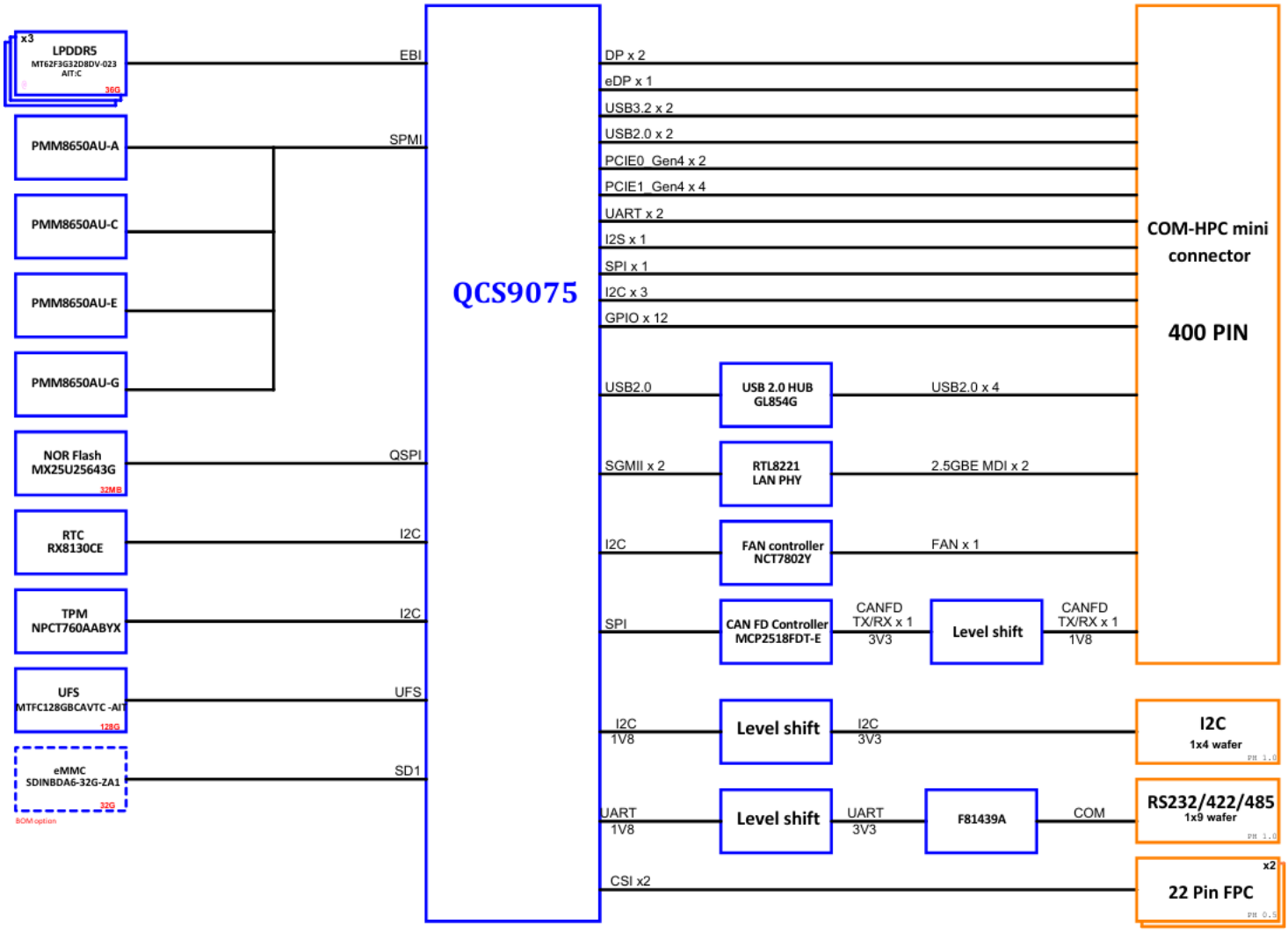
PCB



PCB with Heat Sink & Heat Sink Fan



BLOCK DIAGRAM



PACKING LIST

Part Number	Description	Q'ty
EXMP-Q911-00A1-W1	COM-HPC Mini Module, Qualcomm IQ9075, 36GB RAM, 128GB UFS, 100 TOPS, 8 ~ 20V DC, -40˚C ~ 85˚C, 95 x 70mm	1
EXMP-Q911-00A1-W2	COM-HPC Mini Module, Qualcomm IQ9075, 36GB RAM, 128GB UFS, 100 TOPS, 8 ~ 20V DC, -40˚C ~ 85˚C, W/ Cooler, 95 x 70mm	1

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